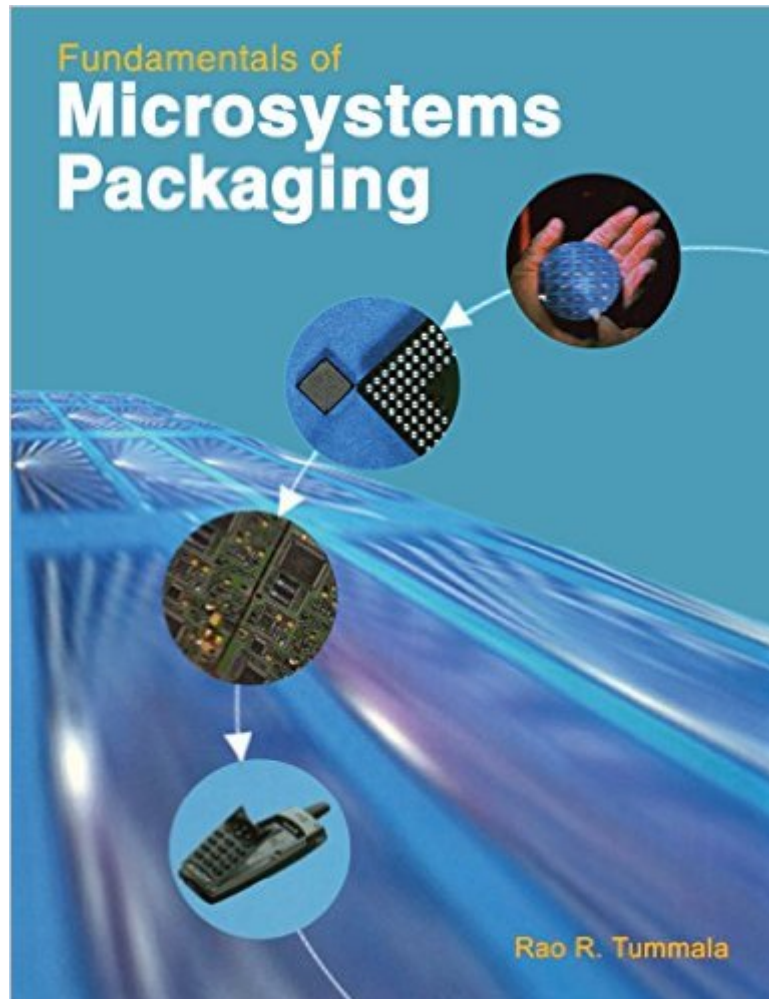


The book was found

Fundamentals Of Microsystems Packaging



Synopsis

LEARN ABOUT MICROSYSTEMS PACKAGING FROM THE GROUND UP Written by Rao Tummala, the field's leading author, *Fundamentals of Microsystems Packaging* is the only book to cover the field from wafer to systems, including every major contributing technology. This rigorous and thorough introduction to electronic packaging technologies gives you a solid grounding in microelectronics, photonics, RF, packaging design, assembly, reliability, testing, and manufacturing and its relevance to both semiconductors and systems. You'll find:

- *Full coverage of electrical, mechanical, chemical, and materials aspects of each technology
- *Easy-to-read schematics and block diagrams
- *Fundamental approaches to all system issues
- *Examples of all common configurations and technologies
 - wafer level packaging, single chip, multichip, RF, opto-electronic, microvia boards, thermal and others
- *Details on chip-to-board connections, sealing and encapsulation, and manufacturing processes
- *Basics of electrical and reliability testing

Book Information

Series: EPI

Hardcover: 967 pages

Publisher: McGraw-Hill Education; 1 edition (May 29, 2001)

Language: English

ISBN-10: 0071371699

ISBN-13: 978-0071371698

Product Dimensions: 7.5 x 1.6 x 9.3 inches

Shipping Weight: 3.6 pounds

Average Customer Review: 3.3 out of 5 stars [See all reviews](#) (3 customer reviews)

Best Sellers Rank: #770,058 in Books (See Top 100 in Books) [#40 in Books > Engineering & Transportation > Engineering > Industrial, Manufacturing & Operational Systems > Industrial Design > Packaging](#) [#226 in Books > Engineering & Transportation > Engineering > Electrical & Electronics > Electronics > Microelectronics](#) [#152272 in Books > Textbooks](#)

Customer Reviews

"Fundamentals of Microsystems Packaging" is an informative, well-written textbook, the first to cover this rapidly-evolving technology. Professor Tummala's latest book should appeal to only three groups: those who know a lot about microsystems packaging, those who know something about it, and those who know nothing about it. Microsystems packaging specialists, who typically focus on one sub-specialty, will find this detailed exposition of the entire field broadening. Non-specialists

with some general packaging knowledge will find here all that they need to fully understand and work with the key elements of microsystems packaging. Novices, students, and those in related technical fields will find a well-structured introduction that prepares them to deal with microsystems packaging. This comprehensive textbook offers to all of the above groups a firm grounding in the diverse disciplines comprising microsystems packaging. Nineteen of the chapters share the title, "Fundamentals of ...". "Fundamental" means "a foundation," and that is what these chapters provide, covering the key elements of topics ranging from semiconductors to systems, including design, processing, materials, manufacture, testing, performance, reliability, thermal management, and environmental considerations. For the specialist, who must build upon these foundations, each chapter includes a judicious selection of recommended further readings. For the autodidact, the scholar, or the flagellant, there are even homework problems to test your knowledge. Four chapters, covering optoelectronics, MEMS, RF packaging, and wafer-level packaging, lead the venturesome to the borders of today's knowledge, where they might glimpse the promised land, or just gape at the dark forests of ignorance.

[Download to continue reading...](#)

Fundamentals of Microsystems Packaging Food Packaging Science and Technology (Packaging and Converting Technology) Practical MEMS: Design of microsystems, accelerometers, gyroscopes, RF MEMS, optical MEMS, and microfluidic systems Fundamentals of Packaging Technology-FOURTH EDITION Fundamentals of Nursing: Human Health and Function (Craven, Fundamentals of Nursing: Human Health and Function raven, Fundamentals of Nurs) Advanced Electronic Packaging: With Emphasis on Multichip Modules (IEEE Press Series on Microelectronic Systems) 3D IC Integration and Packaging Circuits, Interconnections, and Packaging for Vlsi (Addison-Wesley VLSI systems series) Advanced MEMS Packaging Plastic Films: Technology and Packaging Applications What is Packaging Design? (Essential Design Handbook) Packaging Essentials: 100 Design Principles for Creating Packages (Design Essentials) Plastics Packaging 2E: 'Properties, Processing, Applications and Regulations Material Innovation: Packaging Design Cartons, Crates and Corrugated Board: Handbook of Paper and Wood Packaging Technology Modified Atmosphere and Active Packaging Technologies (Contemporary Food Engineering) The Packaging Designer's Book of Patterns Why Shrinkwrap a Cucumber?: The Complete Guide to Environmental Packaging Cartons, Crates and Corrugated Board: Handbook of Paper and Wood Packaging Technology, Second Edition Plastic Packaging: Interactions with Food and Pharmaceuticals

[Dmca](#)